

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S166	69	("1587023" "2981819" "3047438" "3108713" "3160517" "3188459" "3227065" "3239651" "3240915" "3460510" "3502516" "3623712" "3627590" "3661637" "3692572" "3836751" "3913872" "4041278" "4081313" "4097226" "4101759" "4115163" "4151008" "4164643" "4220483" "4224096" "4233493" "4308078" "4315130" "4331485" "4370175" "4375993" "4379727" "4398094" "4421048" "4431459" "4455479" "4493977" "4533820" "4539431" "4540876" "4550245" "4550684" "4567352" "4649261" "4680447" "4698486" "5219786" "5336641" "5399506" "5446825" "5561735" "5908307" "6051483" "6303411" "RE24296").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 11:33
S167	4	oscillat\$4 with frequency with (tunning adjusting regulat\$3) and (heat heating) near2 (local\$5 select\$3) and (ferromagnetic nickel\$1cobalt)	USPAT; EPO; JPO	OR	ON	2005/08/24 11:47
S168	116	oscillat\$4 with frequency and (tunning adjusting regulat\$3) and (heat heating) near2 (local\$5 select\$3 treat\$4) and (ferromagnetic nickel\$1cobalt)	USPAT; EPO; JPO	OR	ON	2005/08/24 11:52
S169	103	(oscillat\$4 frequency) same induct\$3 near2 heating and (tun\$4 adjust\$3 regulat\$3) and (heat heating) near3 (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt)	USPAT; EPO; JPO	OR	ON	2005/08/24 11:56
S170	6	induct\$3 near2 heating and (heat heating) near3 (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co) same (anneal\$3 harden\$3) same (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:03
S171	15	induct\$3 near2 heating and (heat heating) near3 (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co) and (anneal\$3 harden\$3) same (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:07
S172	13	("20010014268" "20010021570" "20020183721" "20030010775" "2393541" "4007369" "4980198" "4983804" "6096149" "6288376" "6368673" "6465281").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 12:05

S17 3	7	induct\$3 near3 heating same (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co) and (anneal\$3 harden\$3) same (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:08
S17 4	6	induct\$3 near3 heating same (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co) and heat\$3 near3 (pin contact spring pad land connector) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:11
S17 5	34	heating with (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co) and heat\$3 near3 (pin contact spring pad land connector) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:13
S17 6	215	heat\$3 with (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co nickel) near4 (pin contact spring pad land connector) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:19
S17 7	418	(induct\$3 electromagnetic frequency) near3 (heating heater heat) and heat\$3 with (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co nickel) and (pin contact spring pad land connector) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:21
S17 8	50	(induct\$3 electromagnetic frequency) near3 (heating heater heat) and heat\$3 with (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co nickel) same (pin contact spring pad land connector) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:33
S17 9	12	("2393541" "3391846" "3462336" "3620875" "3657038" "3941641" "4035547" "4067765" "4762864"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 12:31
S18 0	10	("5124203").URPN.	USPAT	OR	ON	2005/08/24 12:32
S18 1	263	(induct\$3 electromagnetic frequency) near3 (heating heater heat) and heat\$3 near3 (local\$5 treat\$4) and (ferromagnetic nickel\$1cobalt Ni\$1Co nickel) with (substrate board wafer)	USPAT; EPO; JPO	OR	ON	2005/08/24 12:34
S18 2	27	("4239835").URPN.	USPAT	OR	ON	2005/08/24 12:42
S18 3	27	("4239835").URPN.	USPAT	OR	ON	2005/08/29 14:35

S18 4	9	("4987283").URPN.	USPAT	OR	ON	2005/08/29 14:39
S18 5	32	("1975436" "1975437" "2393541" "3391846" "3548140" "3900153" "3902940" "3923580" "4035547" "4107506" "4256945" "4290195" "4327265" "4431891" "4642442" "4659912" "4665309" "4695713" "4749833" "4771151" "4788404" "4789767" "4795870" "4852252" "4914267" "4983804" "4987283"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/29 14:41
S18 6	697	(conductive conducting) near2 (heating heater) and (heat\$1treatment anneal\$3)	USPAT; EPO; JPO	OR	ON	2005/08/29 14:49
S18 7	132	(conductive conducting) near2 (heating heater) and (heat\$1treatment anneal\$3) and (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 14:53
S18 8	27	(inductive inducing) near2 (heating heater) and (heat\$1treatment anneal\$3) and (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 14:55
S18 9	32	(inductive inducing frequency electromagnetic) near5 (heating heater) and ((heat\$3 near2 treat\$4) anneal\$3) same (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 17:12
S19 0	10	("5124203").URPN.	USPAT	OR	ON	2005/08/29 15:29
S19 1	3	("4050269" "4911948" "5740729"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/29 16:31
S19 2	10	("4911948").URPN.	USPAT	OR	ON	2005/08/29 16:32

S19 3	73	("2087480" "2393541" "2760243" "3391846" "3395261" "3461014" "3462336" "3477961" "3507735" "3528867" "3574031" "3620875" "3620876" "3657038" "3709775" "3730804" "3816574" "3900360" "3902940" "3941641" "3996402" "4029837" "4035547" "4090899" "4313777" "4435465" "4521659" "4626642" "4762864" "4859524" "4871412" "4878978" "4969968" "5075034" "5123989" "5124203" "5126521" "5129977" "5240542" "5248864" "5313034" "5338497" "5340428" "5352517" "5357085" "5378879" "5406055" "5412185" "5447592" "5481091" "5483043" "5508496" "5529708" "5538581" "5550511" "5571436" "5624594" "5641422" "5683608").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/29 16:51
S19 4	0	(induct\$3 frequency electromagnetic) near5 (heating heater) and ((heat\$3 near2 treat\$4) anneal\$3) and ferromagnetic with (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 17:14
S19 5	86	(induct\$3 frequency electromagnetic) near5 (heating heater) and ((heat\$3 near2 treat\$4) anneal\$3) and without with (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 17:16
S19 6	309	((heat\$3 near2 treat\$4) anneal\$3) and without with heat\$3 with (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 17:16
S19 7	98	((heat\$3 near2 treat\$4) anneal\$3) same without with heat\$3 with (substrate board)	USPAT; EPO; JPO	OR	ON	2005/08/29 17:16
S19 8	2	"2393541".pn.	USPAT; EPO; JPO	OR	ON	2005/09/01 16:12
S19 9	52	("2393541").URPN.	USPAT	OR	ON	2005/09/01 16:09
S20 0	1	"2457758".pn.	USPAT; EPO; JPO	OR	ON	2005/09/01 16:12
S20 1	2	("2457758").URPN.	USPAT	OR	ON	2005/09/01 17:36
S20 2	1004	(anneal\$3 (heat\$3 near2 treat\$4)) with induct\$3 near3 heat\$3	USPAT	OR	ON	2005/09/01 17:38
S20 3	43	(anneal\$3 (heat\$3 near2 treat\$4)) with induct\$3 near3 heat\$3 and (substrate board wafer) with (contact connector pin land terminal)	USPAT	OR	ON	2005/09/01 17:39
S20 4	5	("5418811").URPN.	USPAT	OR	ON	2005/09/01 18:08